



PK169 (v1.3) December 12, 2018

100% Material Declaration Data Sheet for TQ144 Package

Average Weight : 1.2750 g

Component	Substance Description	CAS # or Description	% of component	Use in product	Component weight / substance weight (in grams)	Component % of total
Silver Epoxy	Silver Powder	7440-22-4	73.5		0.000960	0.07529%
	Epoxy Resin B	Trade Secret	6		0.000076	
	Diluent B	Trade Secret	6		0.000058	
	Epoxy Resin A	9003-36-5	4		0.000038	
	Diluent A	Trade Secret	4		0.000038	
	Hardener	Trade Secret	5		0.000048	
	Dicyandiamide	461-58-5	0.5		0.000005	
	Organic Peroxide	Trade Secret	1		0.000010	
Film					0.000012	0.00094%
	Epoxy Resin A	Trade Secret	10		0.000001	
	Epoxy Resin B	Trade Secret	15		0.000002	
	Phenol Resin	Trade Secret	15		0.000002	
	SiO2 Filler	Trade Secret	45		0.000005	
(Meta)Acrylic Copolymer	Trade Secret	15		0.000002		
Die 1					0.003870	0.30353%
	Silicon	7440-21-3	100.00		0.003870	
Die 2					0.001158	0.09082%
	Silicon	7440-21-3	100.00		0.001158	
Gold Wire					0.000135	0.01059%
	Gold	7440-57-5	99.0475		0.000134	
	Palladium	7440-05-3	0.95		0.000001	
	Calcium	7440-70-2	0.002		0.000000	
	Beryllium	7440-41-7	0.0005		0.000000	
Copper Wire					0.001247	0.09780%
	Copper	7440-50-8	98.08		0.001223	
	Palladium	7440-05-3	1.8		0.000022	
	Gold	7440-57-5	0.12		0.000001	
Mold Compound					1.114842	87.43859%
	Epoxy Resin	Trade Secret	10		0.111484	
	Phenol Resin	Trade Secret	5		0.055742	
	Silica(Amorphous) A	60676-86-0	74		0.824983	
	Silica(Amorphous) B	7631-86-9	10		0.111484	
Carbon Black	1333-86-4	1		0.011148		
Leadframe Tape					0.006000	0.47059%
	NBR	9003-18-3	14		0.000840	
	Phenol resin	28453-20-5	14		0.000840	
	Bismaleimide	79922-55-7	14		0.000840	
	Polyimide film	Trade Secret	58		0.003480	
Leadframe					0.146776	11.51184%
	Nickel Plating	7440-02-0	0.325		0.000477	
	Palladium Plating	7440-05-3	0.0175		0.000026	
	Gold Plating	7440-57-5	0.004		0.000006	
	Copper	7440-50-8	95.5535		0.140250	
	Magnesium	7439-95-4	0.175		0.000257	
	Silicon	7440-21-3	0.725		0.001064	
	Nickel	7440-02-0	3.2		0.004697	

Revision History

Date	Version	Description of Revisions
3/16/2006	1.0	Initial Xilinx release.
7/5/2006	1.1	100% Material Declaration
10/3/2006	1.2	Updated component descriptions.
12/12/2018	1.3	Updated Leadframe component, per XCN18024

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